

FEB 21 2008

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventors: Jian Zhou; Hua Chu
Assignee: Nanometrics Incorporated
Title: Method for Automatically De-Skewing of Multiple Layer Wafer for Improved Pattern Recognition
Application No.: 09/974,721 Filing Date: October 9, 2001
Examiner: Colin M. Larose Group Art Unit: 1765
Docket No.: NAN050 US Confirmation No.: 7841

Saratoga, California
February 21, 2008

Mail Stop Amendment
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO OFFICE ACTION

Dear Sir:

This Response to Office Action is responsive to the November 21, 2007, Office Action, which has a statutorily shortened period for response that ends February 21, 2008. Please enter the following amendments before taking action on the merits of the above-referenced application.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

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